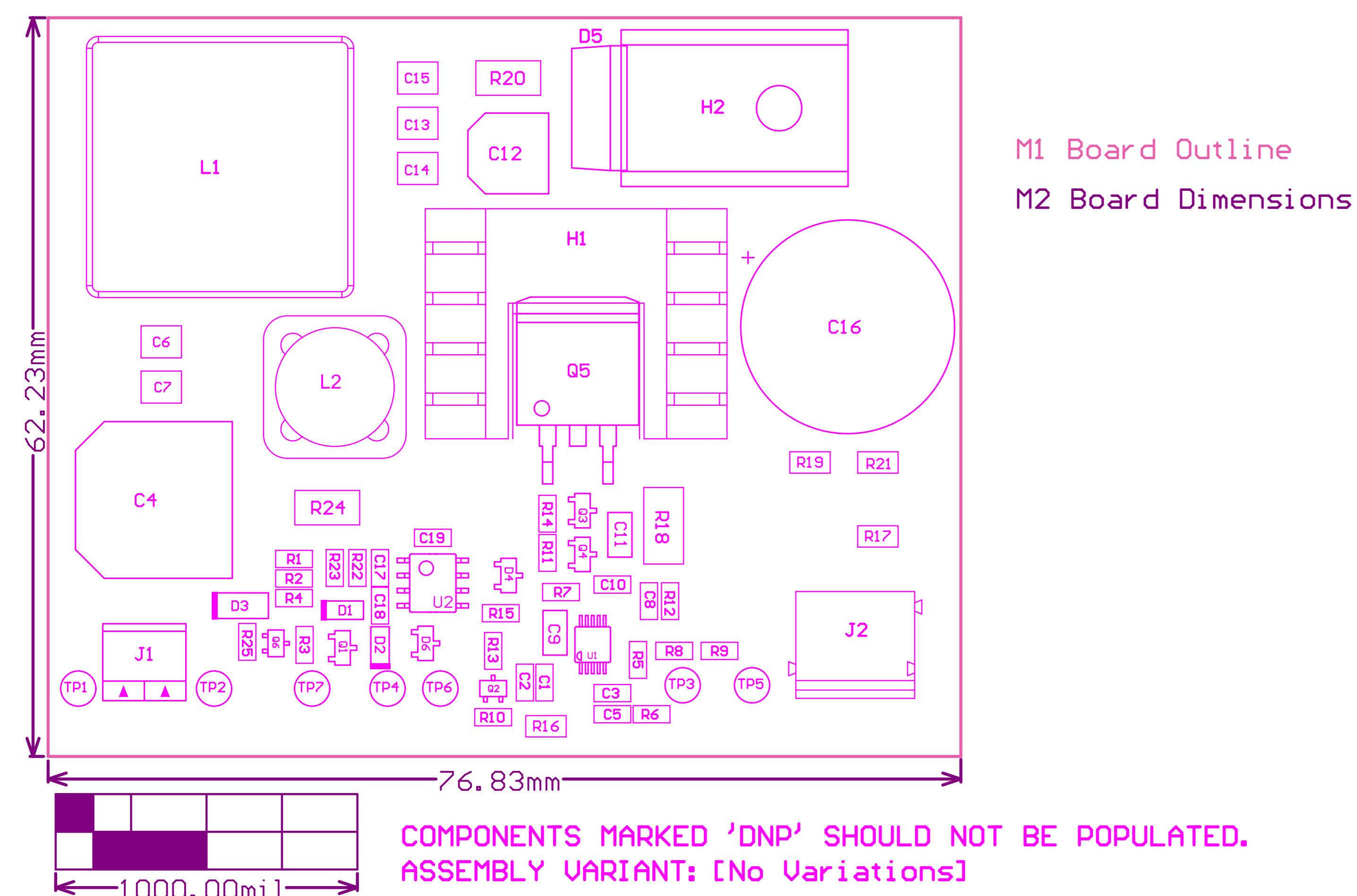


The Reference design PMP30162 Revision B has been built on PMP30162 Revision A PCB



PROJECT TITLE:
180V@0.9A CC and CV Cap Charger SEPIC

DESIGNED FOR:
Public Release

FILE NAME:
PMP30162_Rev_A_PCB.PcbDoc

ENGINEER:
R. Scibilia

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
16.0.9.368

PCB VIEWED FROM TOP SIDE

BOARD #: PMP30162

REV:

SUN REV: Not In VersionControl

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M9 Title Sheet

TID #: .TID

PLOT NAME = Top LayerAssembly Drawing

GENERATED : 2/8/2017 2:39:56 PM

TEXAS INSTRUMENTS

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